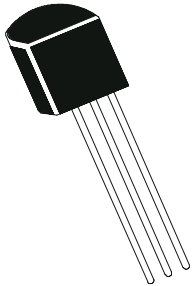


NPN SILICON PLANAR TRANSISTOR

**BF370R
TO-92
BEC**



Low Level Amplifier Transistor.

ABSOLUTE MAXIMUM RATINGS

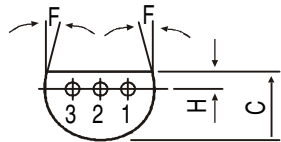
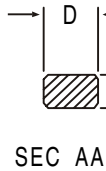
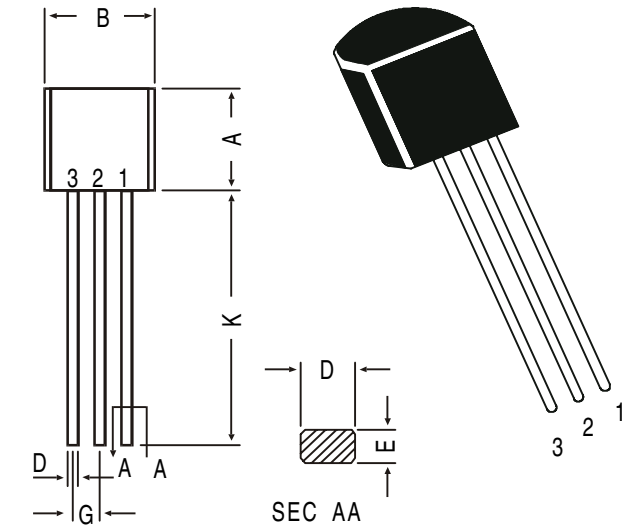
DESCRIPTION		VALUE	UNIT
Collector -Base Voltage	VCBO	40	V
Collector -Emitter Voltage	VCEO	15	V
Emitter Base Voltage	VEBO	4.5	V
Collector Current (Continuous)	IC	100	mA
Power Dissipation @ Ta=25 deg C	PD	500	mW
Derate Above 25 deg C		4.0	mW/deg C
Operating And Storage Junction Temperature Range	Tj, Tstg	-55 to +150	deg C
Lead Temperature for Soldering 1/16" from Body for 10 Seconds.	TL	260	deg C
Thermal Resistance			
Junction to Case	Rth (j-c)	83.3	deg C/W
Junction to Ambient	Rth (j-a)	200	deg C/W

ELECTRICAL CHARACTERISTICS (Ta=25 deg C Unless Otherwise Specified)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Collector -Base Voltage	VCBO	IC=100uA, IE=0	40	-	-	V
Collector -Emitter Voltage	VCEO	IC=100uA, IB=0	15	-	-	V
Emitter Base Voltage	VEBO	IE=100uA, IC=0	4.5	-	-	V
Collector Cut off Current	ICBO	VCB=20V, IE=0 Ta=125 deg C	-	-	400	nA
Emitter Cut off Current	IEBO	VEB=2V, IC=0	-	-	100	nA
DC Current Gain	hFE	IC=10mA, VCE=1V	40	-	-	
DYNAMIC CHARACTERISTICS						
Transistors frequency	ft	IC=10mA, VCE=10V	500	-	-	MHz
		IC=40mA, VCE=10V	490	-	-	MHz
Collector Capacitance	Cc	VCB=10V, IE=0, f=1MHz	Typ 2.2			pF
Emitter Capacitance	Ce	VEB=1V, IC= Ic=0, f=1MHz	-	-	4.5	pF
Feedback Capacitance	Cre	IC=0, VCE=10V, f=1MHz	Typ 1.6			pF
Interference Voltage for K=1%	GV	V(int) RMS	Typ 120			mV

TO-92 Plastic Package

TO-92 Transistors on Tape and Ammo Pack

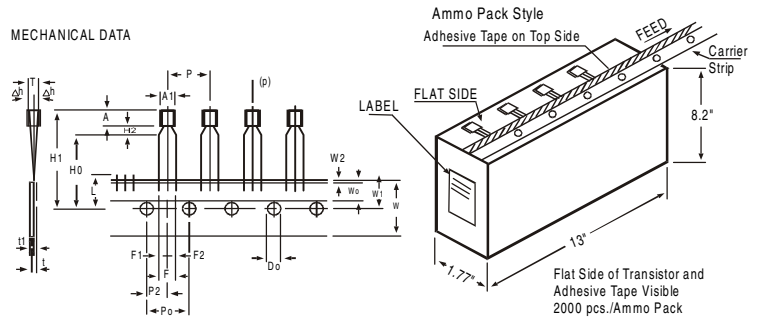


PIN CONFIGURATION

1. BASE
2. EMITTER
3. COLLECTOR

All dimensions in mm.

DIM	MIN.	MAX.
A	4.32	5.33
B	4.45	5.20
C	3.18	4.19
D	0.41	0.55
E	0.35	0.50
F	5 DEG	
G	1.14	1.40
H	1.14	1.53
K	12.70	—



All dimensions in mm unless specified otherwise

ITEM	SYMBOL	SPECIFICATION				REMARKS
		MIN.	NOM.	MAX.	TOL.	
BODY WIDTH	A1	4.0		4.8		
BODY HEIGHT	A	4.8		5.2		
BODY THICKNESS	T	3.9		4.2		
PITCH OF COMPONENT	P		12.7		±1	
FEED HOLE PITCH	Po		12.7		±0.3	CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH
FEED HOLE CENTRE TO COMPONENT CENTRE	P2		6.35		±0.4	TO BE MEASURED AT BOTTOM OF CLINCH
DISTANCE BETWEEN OUTER LEADS	F		5.08		+0.6 -0.2	
COMPONENT ALIGNMENT	Δh		0	1		AT TOP OF BODY
TAPE WIDTH	W		18		±0.5	
HOLD-DOWN TAPE WIDTH	Wo		6		±0.2	
HOLE POSITION	W1		9		+0.7 -0.5	
HOLD-DOWN TAPE POSITION	W2		0.5		±0.2	
LEAD WIRE CLINCH HEIGHT	Ho		16		±0.5	
COMPONENT HEIGHT	H1		23.25			
LENGTH OF SNIPPED LEADS	L		11.0			
FEED HOLE DIAMETER	Do		4		±0.2	
TOTAL TAPE THICKNESS	t		1.2			t1 0.3 - 0.6
LEAD - TO - LEAD DISTANCE F1,	F2		2.54		+0.4 -0.1	
CLINCH HEIGHT	H2			3		
PULL - OUT FORCE	(P)	6N				

NOTES

1. MAXIMUM ALIGNMENT DEVIATION BETWEEN LEADS NOT TO BE GREATER THAN 0.2 mm.
2. MAXIMUM NON-CUMULATIVE VARIATION BETWEEN TAPE FEED HOLES SHALL NOT EXCEED 1 mm IN 20 PITCHES.
3. HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO EXPOSURE OF ADHESIVE.
4. NO MORE THAN 3 CONSECUTIVE MISSING COMPONENTS ARE PERMITTED.
5. A TAPE TRAILER, HAVING AT LEAST THREE FEED HOLES ARE REQUIRED AFTER THE LAST COMPONENT.
6. SPLICES SHALL NOT INTERFERE WITH THE SPROCKET FEED HOLES.

Packing Detail

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5.0K	17" x 15" x 13.5"	80.0K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2.0K	17" x 15" x 13.5"	32.0K	12.5 kgs

Notes

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Discrete Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished on the CDIL Web Site/CD is believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Discrete Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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